

TSMC Enhances 0.13 μ m Family

Area reduction and performance gain with slim platform for analog and power management system-on-chip applications

Hsinchu, Taiwan, R.O.C. – June 29, 2009 - Taiwan Semiconductor Manufacturing Company, Ltd. (TWSE: 2330, NYSE: TSM) today announced that it has released an enhanced version of its 0.13 μ m process to benefit customers' cost and competition and to enable the integration of power management functions. The 0.13 μ m/0.11 μ m family now includes a slim standard cell, SRAM and I/O with substantial area reduction and the 0.13 μ m process also adopts LD-MOS (5V~20V) on RF platforms to enable analog and power management applications. The slim platform is available in the third quarter this year while the LD-MOS on RF platforms will be available in Q4 this year.

To meet the ever shrinking requirements for basic consumer and RF applications, the slim platform I/O area achieves a 30% reduction and SRAM bit cells demonstrate a 25% reduction when compared with traditional offerings. Furthermore, a 0.13 μ m LD-MOS device built upon a RF platform enables SOC designs with power management functionality.

“This is another example of how TSMC is committed to enabling more efficient SoC design of wireless, consumer and communications devices using 0.13 μ m process technology,” said Dr. Simon Wang, senior director of Advanced Technology Business Division. “The result of these enhancements will spawn the next generation of innovation,” he said.

TSMC's investment in R&D for technology and IP portfolios within the 0.13 μ m /0.11 μ m family now delivers a true 5V with Copper interconnect for the integration of analog, high-speed DSP, power management and watt-scale class-D amplification. Along with new features development for system-on-chip design, TSMC also offers a shrunken path to enhance customer's competitiveness including sub-node and slim technology platform.

About TSMC

TSMC is the world's largest dedicated semiconductor foundry, providing the industry's leading process technology and the foundry's largest portfolio of process-proven libraries, IP, design tools and reference flows. The Company's total managed capacity in 2008 exceeded 9 million 8-inch equivalent wafers, including capacity from two advanced 12-inch - GIGAFABs™, four eight-inch fabs, one six-inch fab, as well as TSMC's wholly owned subsidiaries, WaferTech and TSMC (China), and its joint venture fab, SSMC. TSMC is the first foundry to provide 40nm production capabilities. Its corporate headquarters are in Hsinchu, Taiwan. For more information about TSMC please visit <http://www.tsmc.com>.

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